

Investigation of Illuminated High-Frequency Capacitance-Voltage Response in Deep Depletion of HfO₂ and SiO₂ MOS Capacitors with Ultra-thin Gate Oxides

Jen-Yuan Cheng and Jenn-Gwo Hwu*

Graduate Institute of Electronics Engineering / Department of Electrical Engineering
Room 446, EEII, National Taiwan University, Taipei, Taiwan, R.O.C.

*Phone: + 886-2-33663646 E-mail: hwu@cc.ee.ntu.edu.tw

1. Introduction

Deep depletion in MOS structure is so far of use for the characterization of the interface properties [1-2]. Recently, we have demonstrated the edge enhanced deep depletion MOS photodiode by high-*k* material [3]. The photonic application of deep depletion is of interest. Based on the concept of local depletion capacitance (LDC), deep depletion reveals that localized area formed by injection carriers from substrate can be observed clearly in magnified *C-V* curves [4]. However, the correlation between photonic *C-V* curves and deep depletion in high-*k* stack is lack of discussion.

In this work, we examine illuminated *C-V* curves via LDC model. The smaller initiation voltage of deep depletion in HfO₂ is observed from magnified *C-V* curves. The non-uniform area ratio increases in HfO₂ and SiO₂ device after the illumination was also investigated.

2. Experimental

For SiO₂, ultra-thin oxides were grown through the tilted anodization process with applied DC voltage of 12.5V. Post-oxidation annealing was carried out in 100 torr, N₂, at 850 °C for 15 secs. For HfO₂, after initial SiO₂ layer was grown by RTP at 950 °C for 15s with 15 torr O₂ ambient, the sample was sputtered with Hf metal at 400V, 0.15A (60W) for 2 mins. The Hf layer was oxidized in 50% HNO₃ for 6 mins to form HfO₂ then annealed by N₂ ambient at 380 °C for 12 mins. After each oxidation process, pure Al was thermally evaporated as gate electrode. The gate area of 2.25×10^{-4} cm² was defined. Finally, Al was thermally evaporated on backside as back contact. The overall process flows of MOS capacitors with SiO₂ and HfO₂ are shown in Fig. 1 (a) and (b), respectively. *C-V* characteristics were measured by an HP4284 LCR meter, and illuminated *C-V* curves are also derived by using 13W Circular Fluorescent Microscope Illuminator (Coherent's Model 9, CFMI). From correction model proposed by Hu [5], EOTs of gate dielectric was extracted by fitting the corrected *C-V* curves based on 1 MHz and 100 KHz with the consideration of quantum mechanical effect.

3. Simulation Result and Discussion

Fig.2 and 3 show the *C-V* curves of SiO₂ and HfO₂ with illumination and dark measurement, respectively. The inset of the Fig. 2 and 3 manifests the *C-V* curves and show the different initiation voltages of deep depletion in corresponding devices. Clearly, the initiation voltage of deep depletion in HfO₂ is smaller than the SiO₂ in both illumi-

nated and dark *C-V* curves under large bias. We then subtract the capacitance of dark from illuminated *C-V* curves as shown in Fig.4. The peak of the diagram indicated the initiation voltages of SiO₂ and HfO₂ are 1.6V and 0.12V, respectively. Previous research shows the saturated inversion current occurs earlier in HfO₂ than in SiO₂ under the same condition (EOT, bias) [6], which are consistent with the result found in this work. Fig. 5 and 6 show the fitting *C-V* curves via LDC model [2, 4]. Both of them were perfectly fitted and the fitting curves are shown in solid lines. Interestingly, the uniform area ratio (*K*) decreases after illumination in both SiO₂ (from *K*=0.97 to 0.75) and HfO₂ device (from *K*=0.75 to 0.66). In the deep depletion mode without illumination, the variation of the capacitance is mainly caused by the depleted acceptor charges. Due to the built-up of photoexcited excess electrons at SiO₂/Si hetero interface (the photovoltaic effect), the reduced surface potential result in the shrinkage of depletion width with increasing of the capacitance as illustrated in schematic diagram in Fig.7. Furthermore, in our latest research [3], the charge collection phenomena at edge in MOS device indicated the inversion tunneling current was dominated by the geometrical perimeter of the device, i.e., the tunneling induced deep depletion expansion-shrinkage has been enhanced by the edge field of abrupt junction in the hetero structure during the illumination. It is believed that the lateral non-uniformity effect (non-uniform area ratio) has been manifested on the illuminated *C-V* curves.

4. Conclusions

The correlation between illuminated *C-V* response and deep depletion of SiO₂ and HfO₂ was demonstrated. The HfO₂ shows the earlier occurrence of deep depletion than SiO₂ device at the same EOT. The electrical characterization of deep depletion (LDC model) in dielectric stack indicated the non-uniform effect in MOS structure was manifested during the illumination.

Acknowledgements

This work was supported by the National Science Council, ROC, under Contract No. NSC96-2628-E-002-246-MY3..

References

- [1] C. H. Chang, et al., J. Appl. Phys. **105** (2009) 094103.
- [2] J. Y. Cheng, et al., J. Appl. Phys. **106** (2009) 074057.
- [3] J. Y. Cheng, et al., Appl. Phys. Lett. (2010), in press.
- [4] J. Y. Cheng, et al., ECS. Trans. **25** (2009) 307.
- [5] K. J. Yang, et al., EDL. **46** (1999) 1500.
- [6] C. H. Chen, et al., T-ED. **56** (2009) 1262.

- 100 P-type Si with RCA clean
- Ultra-thin SiO₂ grown by Anodization
- POA at 850°C, 15sec
- Aluminum gate electrode evaporation
- Gate patterning
- Aluminum back contact
- (a)
- 100 P-type Si with RCA clean
- Interfacial layer SiO₂ grown by RTO
- Hf metal deposition by sputter
- Nitride acid oxidation (NAO) of Hf metal
- RTA at 380°C, 12mins
- Aluminum gate electrode evaporation
- Gate patterning
- Aluminum back contact
- (b)

Fig. 1 Fabrication flow of MOS capacitors with SiO₂ and HfO₂ dielectrics

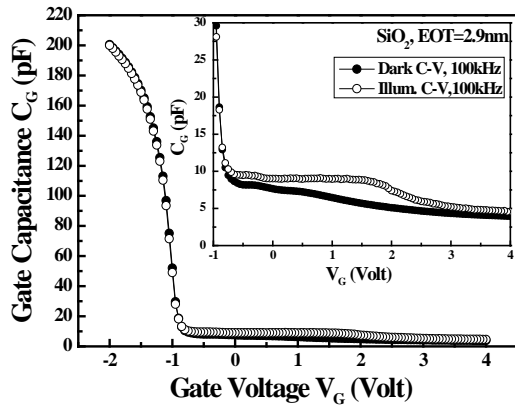


Fig.2 Illuminated C-V curves of SiO₂ (EOT=2.9nm) under 100kHz measurement. C-V curves in the deep depletion region is enlarged in the inset.

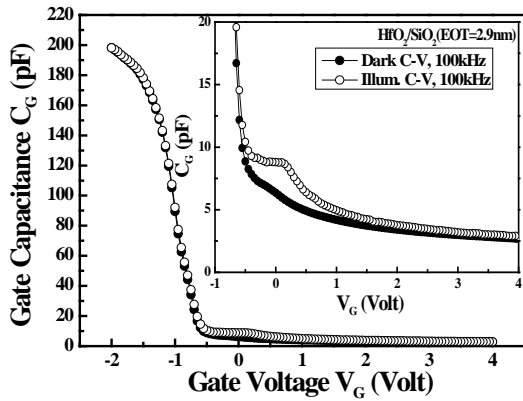


Fig.3 Illuminated C-V curves of HfO₂ (EOT=2.9nm) under 100kHz measurement. C-V curves in the deep depletion region are enlarged in the inset.

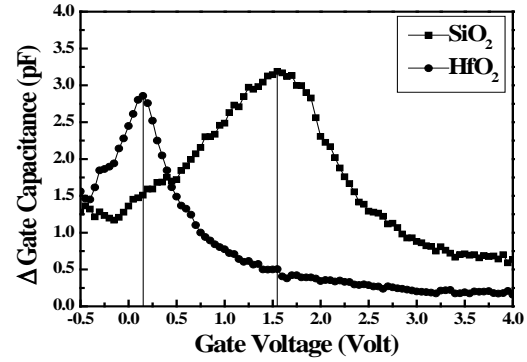


Fig.4 Variation of gate capacitance from C-V curves before and after illumination. The initiation voltages of deep depletion in HfO₂ and SiO₂ are 0.12V and 1.6V, respectively.

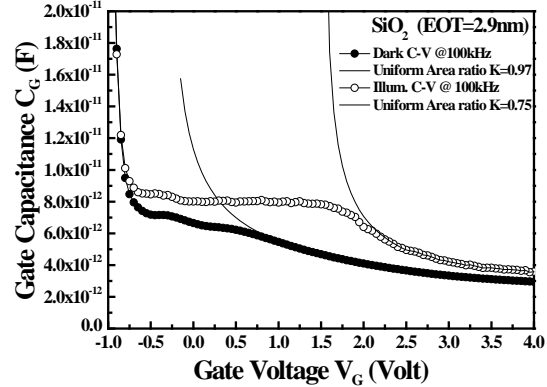


Fig.5 C-V curves of SiO₂ in the deep depletion. The solid lines show the calculated C-V curves by LDC model. K=0.97 and 0.75 for dark and illuminated C-V curves, respectively.

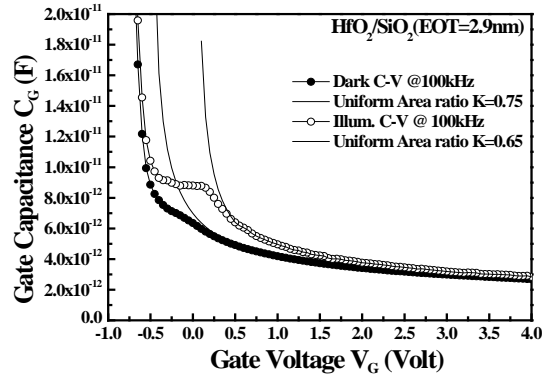


Fig.6 C-V curves of HfO₂ in the deep depletion. The solid lines show the calculated C-V curves by LDC model. K=0.75 and 0.65 for dark and illuminated C-V curves, respectively.

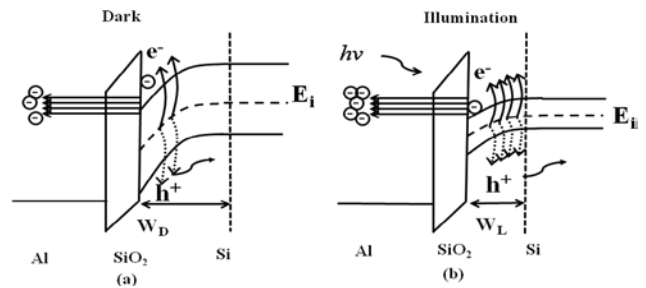


Fig.7 Schematic energy band diagrams for Al-SiO₂-Si structure in deep depletion under (a) darkness and (b) illumination.